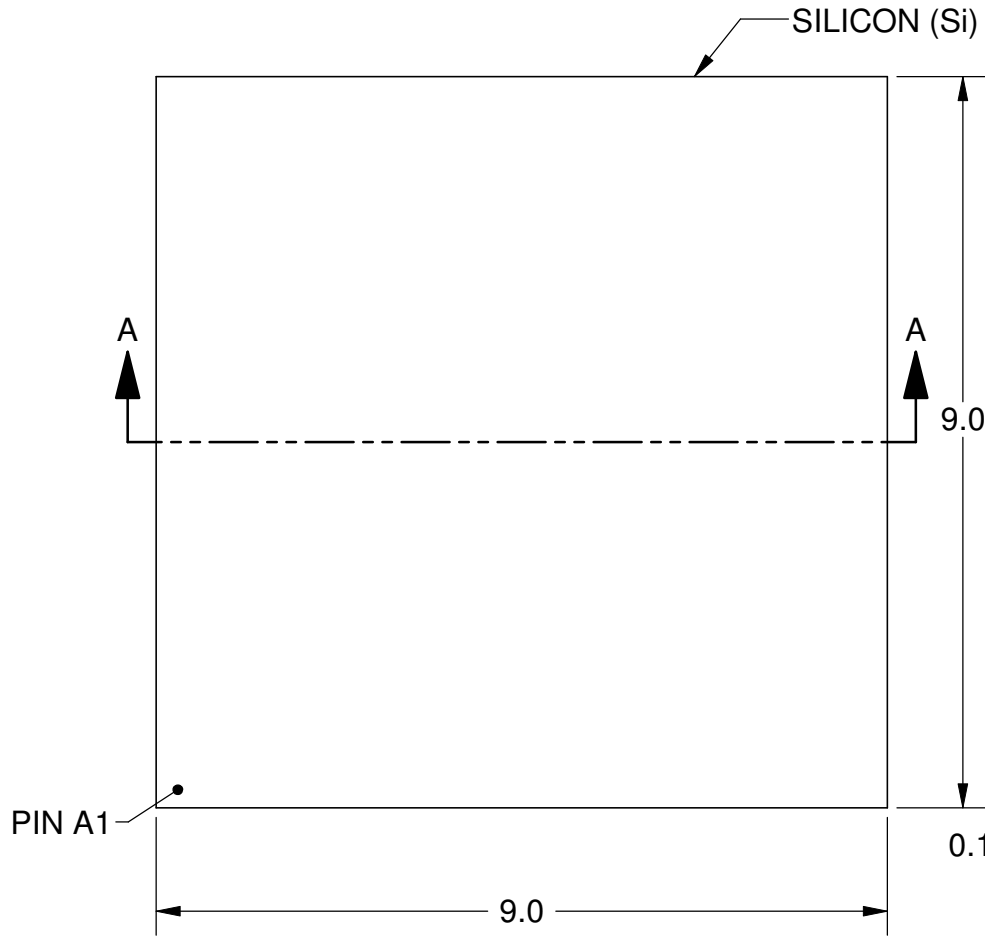
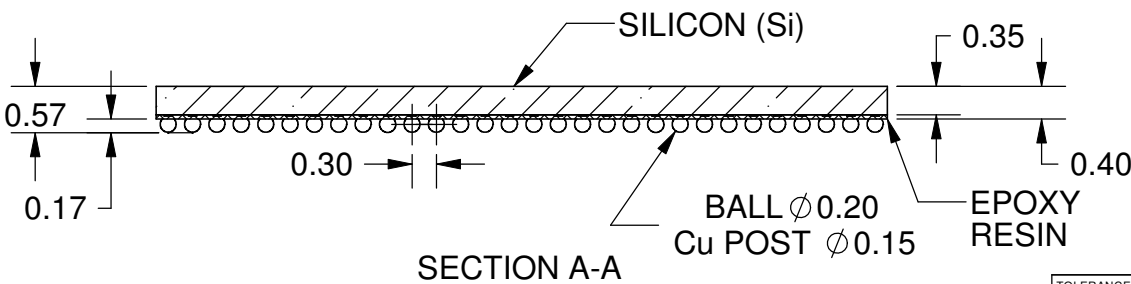
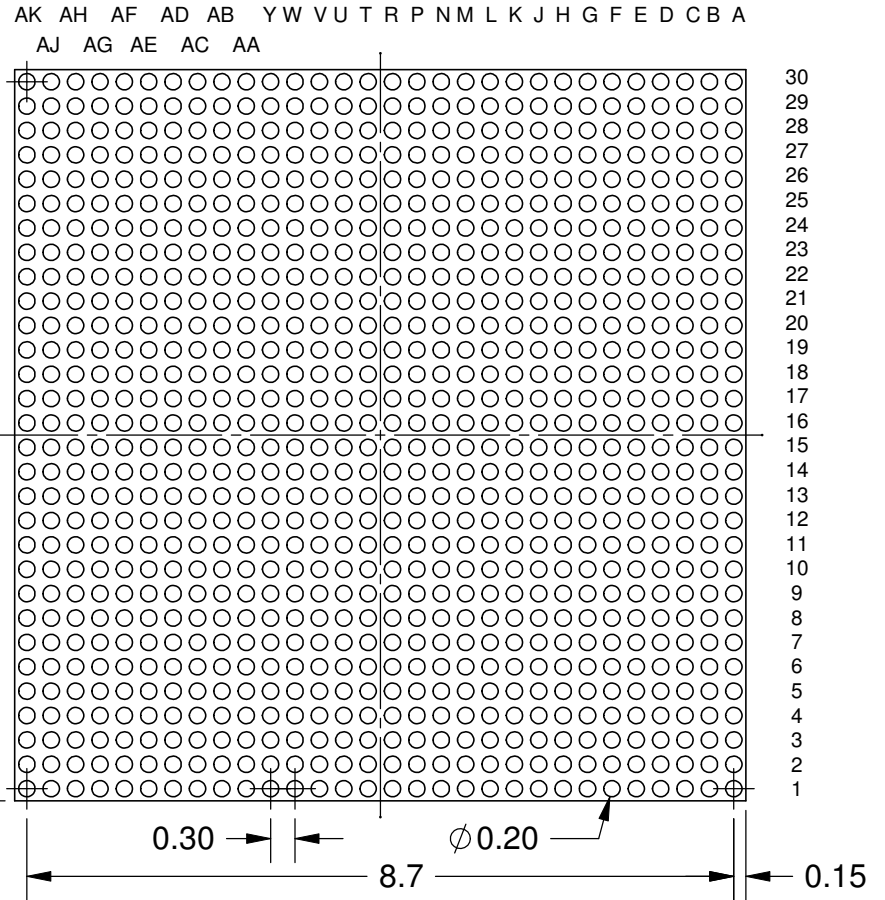


TOP VIEW



BALL VIEW



Notes: (Unless Otherwise Specified).

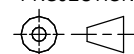
- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY:
STANDARD: SAC305 (Sn96.5/Ag3.0/Cu0.5).
SPECIAL: LF35 (Sn98.3/Ag1.2/Cu0.5).
- 3) BALL DIAMETER (BEFORE REFLOW): 0.20mm.
- 4) NON-SOLDER MASK DEFINED PAD.
- 5) PAD Cu DIAMETER: 0.15mm.
- 6) SUBSTRATE MATERIAL: Si (SILICON).
- 7) DAISY CHAIN PATTERN (SEE PAGE 2).

PART NUMBER TABLE

PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
WLP900T.3C-DC307D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
WLP900T.3C1-DC307D	Sn98.3/Ag1.2/Cu0.5	YES	YES	YES

TOLERANCE UNLESS NOTED	
X.X	+/- 0.3
X.XX	+/- 0.03
X.XXX	+/- 0.003
ANGLES	+/- 0.5°
ALL DIMENSIONS IN	
<input type="checkbox"/> INCHES	<input checked="" type="checkbox"/> MILLIMETERS

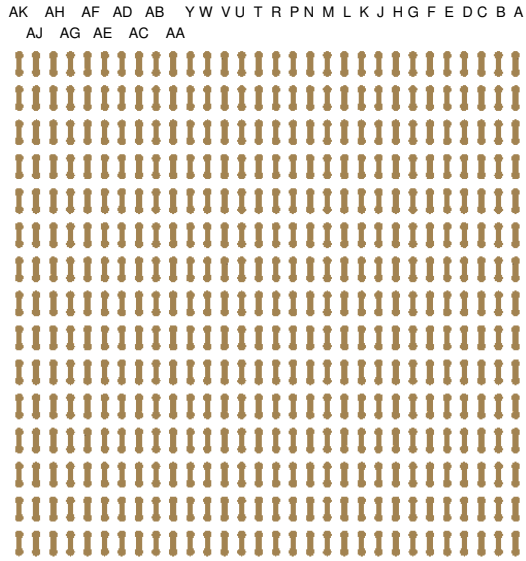
THIRD ANGLE PROJECTION



APPROVALS	DATE
DRAWN J. Hines	12/29/2010
ENG	
MFG	
QA	
CUST	
REVISED	

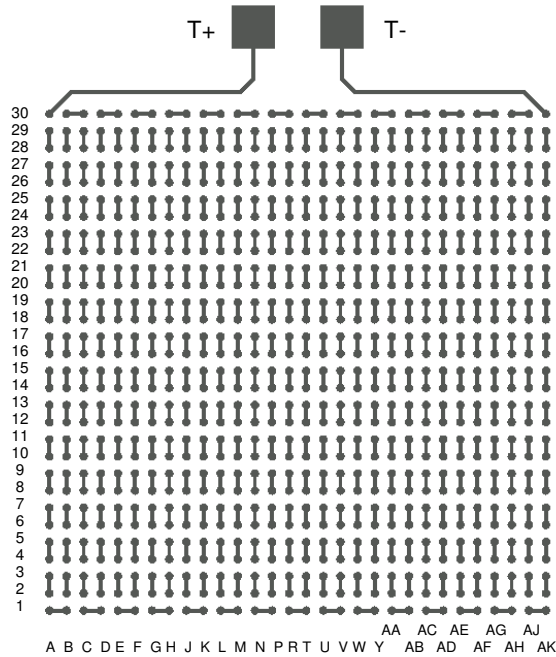
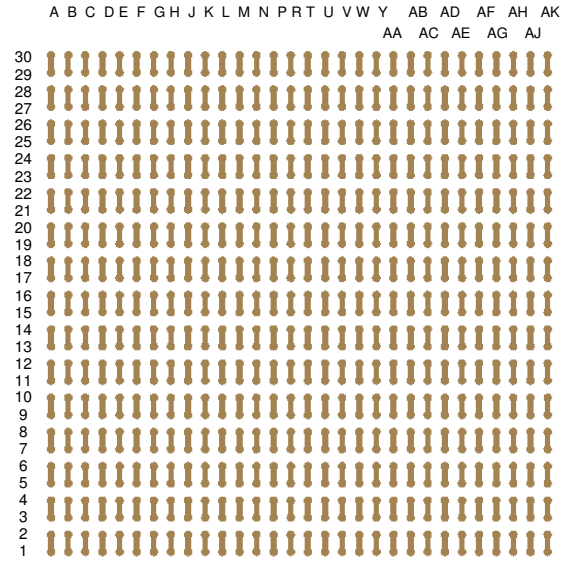
TopLine ®			
TITLE WLP900T.3C-DC307D 900-BALL P=0.3mm (TEG0306)			
SCALE	SIZE	DRAWING NO.	REV
10.75:1	A	533072	A
DO NOT SCALE DRAWING			SHEET 1 OF 2

DAISY CHAIN PATTERN



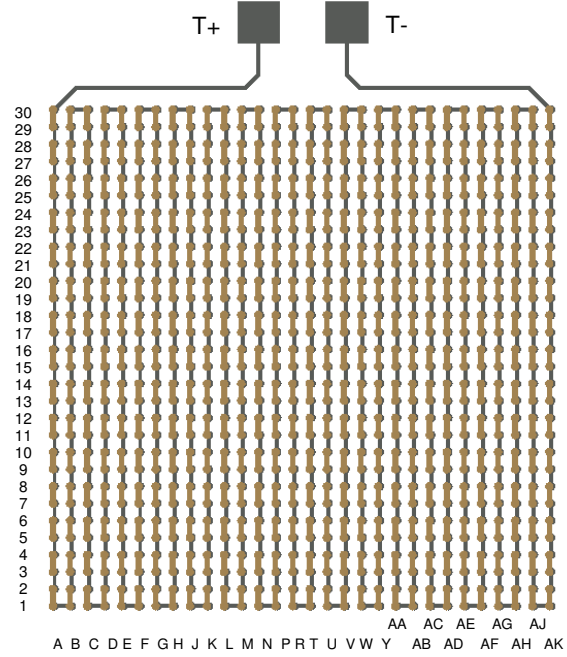
BALL VIEW

BOTTOM SIDE
(TOP X-RAY VIEW)



TOP VIEW

AFTER MOUNTING
TO TEST BOARD
(TOP X-RAY VIEW)



TEST VEHICLE BOARD

Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.15mm (5.9mil).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.07mm (3mil).

TopLine ®			
TITLE WLP900T.3C-DC307D 900-BALL P=0.3mm (TEG0306)			
SCALE 7.55:1	SIZE A	DRAWING NO. 533072	REV A
DO NOT SCALE DRAWING		SHEET 2 OF 2	